CD54ACT08 . . . F PACKAGE CD74ACT08 . . . E OR M PACKAGE

SCHS312B - JANUARY 2001 - REVISED JUNE 2002

9 🛛 3A

8 🛛 3Y

- Inputs Are TTL-Voltage Compatible
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- **Balanced Propagation Delays**
- **Buffered Inputs**
- ±24-mA Output Drive Current - Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and **Circuit Design**
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

description

(TOP VIEW) 1A [14 Vcc 1B П 13 🛛 4B 2 1Y [12 🛛 4A 3 2A 🛛 4 11 🛛 4Y 2B 🛛 5 10 🛛 3B 2Y 🛛

6

GND 🛛 7

The 'ACT08 devices are quadruple 2-input positive-AND gates. These devices perform the Boolean function $Y = A \bullet B$ or $Y = \overline{\overline{A} + \overline{B}}$ in positive logic.

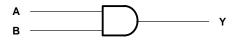
| TA | PAC | KAGE [†] | ORDERABLE PART NUMBER | TOP-SIDE MARKING | | | | | | | |
|----------------|----------|-------------------|--------------------------|---------------------|--|--|--|--|--|--|--|
| | PDIP – E | Tube | CD74ACT08E | CD74ACT08E | | | | | | | |
| –55°C to 125°C | SOIC – M | Tube | CD74ACT08M | ACT08M | | | | | | | |
| -55°C to 125°C | 30IC - M | Tape and reel | CD74ACT08M96 | ACTUON | | | | | | | |
| | CDIP – F | Tube | CD54ACT08F3A | CD54ACT08F3A | | | | | | | |

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design quidelines are available at www.ti.com/sc/package.

| FUNCTION TABLE (each gate) | | | | | | | | | | |
|-------------------------------|---------------|---|--|--|--|--|--|--|--|--|
| INP | INPUTS OUTPUT | | | | | | | | | |
| Α | В | Y | | | | | | | | |
| н | Н | Н | | | | | | | | |
| L | Х | L | | | | | | | | |
| Х | L | L | | | | | | | | |

logic diagram, each gate (positive logic)





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SCHS312B - JANUARY 2001 - REVISED JUNE 2002

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

| Supply voltage range, V _{CC} | –0.5 V to 6 V |
|---|----------------|
| Input clamp current, I _{IK} (V _I < 0 or V _I > V _{CC}) (see Note 1) | |
| Output clamp current, I_{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1) | |
| Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$ | ±50 mA |
| Continuous current through V _{CC} or GND | ±100 mA |
| Package thermal impedance, θ_{JA} (see Note 2): E package | 80°C/W |
| M package | |
| Storage temperature range, T _{stg} | –65°C to 150°C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

| | | T _A = 25°C | | | –40°C TO 85°C | | C TO °C | UNIT |
|---------------------|------------------------------------|-----------------------|-----|-----|------------------|-----|------------|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| VCC | Supply voltage | 4.5 | 5.5 | 4.5 | 5.5 | 4.5 | 5.5 | V |
| VIH | High-level input voltage | 2 | | 2 | | 2 | | V |
| VIL | Low-level input voltage | | 0.8 | | 0.8 | | 0.8 | V |
| VI | Input voltage | 0 | VCC | 0 | VCC | 0 | VCC | V |
| Vo | Output voltage | 0 | VCC | 0 | VCC | 0 | VCC | V |
| ЮН | High-level output current | | -24 | | -24 | | -24 | mA |
| IOL | Low-level output current | | 24 | | 24 | | 24 | mA |
| $\Delta t/\Delta v$ | Input transition rise or fall rate | | 10 | | 10 | | 10 | ns/V |

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | Vcc | T _A = 2 | 25°C | –40°C TO 85°C | | –55°C TO 125°C | | UNIT | | | | |
|-----------|---|--------------------------------------|--|--|-------------|------------------|-------------------------|-------------------|------|------|--|------|--|-----|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | | | | | | |
| | | I _{OH} = -50 μA | 4.5 V | 4.4 | | 4.4 | | 4.4 | | | | | | |
| Vau | $\lambda = \lambda + \sigma \lambda + \sigma$ | I _{OH} = -24 mA | 4.5 V | 3.94 | | 3.8 | | 3.7 | | V | | | | |
| ∨он | $V_{I} = V_{IH} \text{ or } V_{IL}$ | $I_{OH} = -50 \text{ mA}^{\ddagger}$ | 5.5 V | | | | | 3.85 | | v | | | | |
| | | $I_{OH} = -75 \text{ mA}^{\ddagger}$ | 5.5 V | | | 3.85 | | | | | | | | |
| | | I _{OL} = 50 μA | 4.5 V | | 0.1 | | 0.1 | | 0.1 | | | | | |
| N/ | | $\lambda = \lambda = 0$ | M = M + or M + | M = M + or M + | V. – V or V | V. – V or V | I _{OL} = 24 mA | 4.5 V | | 0.36 | | 0.44 | | 0.5 |
| VOL | $V_{I} = V_{IH} \text{ or } V_{IL}$ | I _{OL} = 50 mA‡ | 5.5 V | | | | | | 1.65 | v | | | | |
| | | IOL = 75 mA‡ | 5.5 V | | | | 1.65 | | | | | | | |
| l | $V_I = V_{CC} \text{ or } GND$ | | 5.5 V | | ±0.1 | | ±1 | | ±1 | μA | | | | |
| ICC | $V_I = V_{CC}$ or GND, | I <mark>O</mark> = 0 | 5.5 V | | 4 | | 40 | | 80 | μA | | | | |
| ΔICC | $V_{I} = V_{CC} - 2.1 V$ | | 4.5 V to 5.5 V | | 2.4 | | 2.8 | | 3 | mA | | | | |
| Ci | | | | | 10 | | 10 | | 10 | pF | | | | |

[‡] Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.



SCHS312B – JANUARY 2001 – REVISED JUNE 2002

ACT INPUT LOAD TABLE

| INPUT | UNIT LOAD |
|-----------------------------|--------------------|
| A or B | 0.3 |
| Unit load is ΔI_{C} | CC limit specified |
| in electrical | characteristics |

table (e.g., 2.4 mA at 25°C).

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

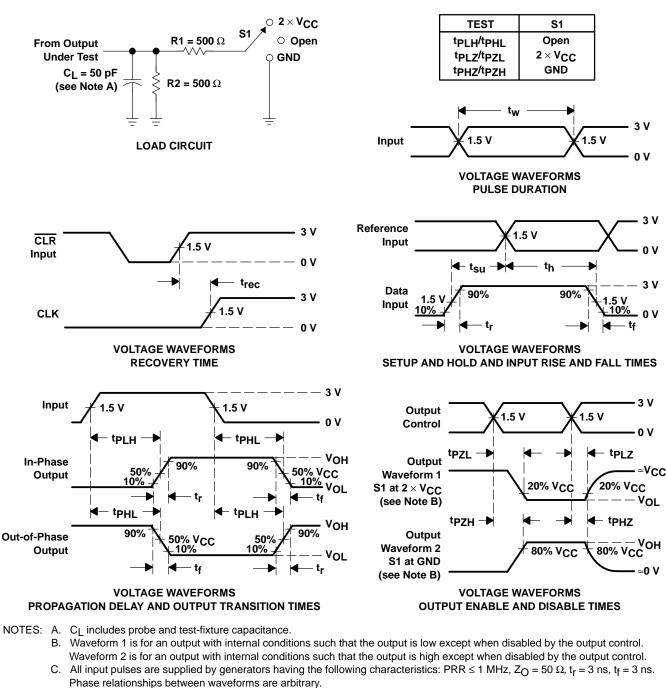
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | –40°C 85° | | –55°C 125 | | UNIT |
|------------------|-----------------|----------------|--------------|------|--------------|------|------|
| | | (001-01) | MIN | MAX | MIN | MAX | |
| ^t PLH | A or B | V | 3.3 | 11.7 | 3.2 | 12.9 | |
| ^t PHL | AUB | I | 3.3 | 11.7 | 3.2 | 12.9 | ns |

operating characteristics, V_{CC} = 5 V, T_A = 25° C

| | PARAMETER | TYP | UNIT |
|-----|-------------------------------|-----|------|
| Cpd | Power dissipation capacitance | 50 | pF |

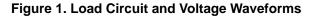


SCHS312B - JANUARY 2001 - REVISED JUNE 2002



PARAMETER MEASUREMENT INFORMATION

- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLH and tpHL are the same as t_{pd} .
- G. t_{PZL} and t_{PZH} are the same as t_{en} .
- H. tpLZ and tpHZ are the same as tdis.







PACKAGING INFORMATION

| Orderable Device | Status | Package Type | Package | Pins | Package | Eco Plan | Lead/Ball Finish | MSL Peak Temp | Op Temp (°C) | Device Marking | Samples |
|------------------|--------|--------------|---------|------|---------|----------------------------|------------------|--------------------|--------------|----------------|---------|
| | (1) | | Drawing | | Qty | (2) | (6) | (3) | | (4/5) | |
| CD54ACT08F3A | ACTIVE | CDIP | J | 14 | 1 | TBD | Call TI | N / A for Pkg Type | -55 to 125 | CD54ACT08F3A | Samples |
| CD74ACT08E | ACTIVE | PDIP | Ν | 14 | 25 | Green (RoHS & no Sb/Br) | NIPDAU | N / A for Pkg Type | -55 to 125 | CD74ACT08E | Samples |
| CD74ACT08M | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | ACT08M | Samples |
| CD74ACT08M96 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | ACT08M | Samples |
| CD74ACT08ME4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | ACT08M | Samples |
| CD74ACT08MG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | NIPDAU | Level-1-260C-UNLIM | -55 to 125 | ACT08M | Samples |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.



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6-Feb-2020

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OTHER QUALIFIED VERSIONS OF CD54ACT08, CD74ACT08 :

- Catalog: CD74ACT08
- Military: CD54ACT08

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

P1

(mm)

8.0

K0 (mm)

2.1

w

(mm)

16.0

Pin1

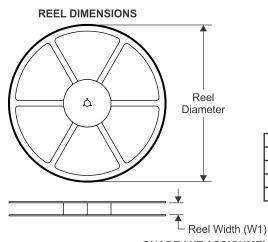
Quadrant

Q1

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TAPE AND REEL INFORMATION



CD74ACT08M96

SOIC

D



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



330.0

16.4

6.5

9.0

| All dimensions are nominal | | | | | | | | |
|----------------------------|-----------------|--------------------|--|--------------------------|--------------------------|------------|------------|---|
| Device | Package Type | Package Drawing | | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | , |
| | | | | | | | | |

14

2500

TEXAS INSTRUMENTS

www.ti.com

PACKAGE MATERIALS INFORMATION

26-Jan-2013



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD74ACT08M96 | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |

GENERIC PACKAGE VIEW

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



J0014A

EXAMPLE BOARD LAYOUT

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE





D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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